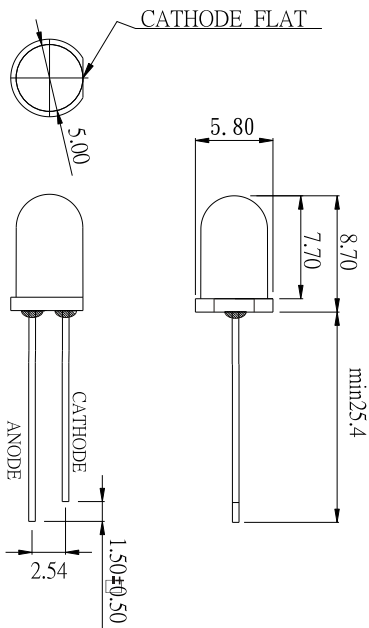


Device Selection Guide

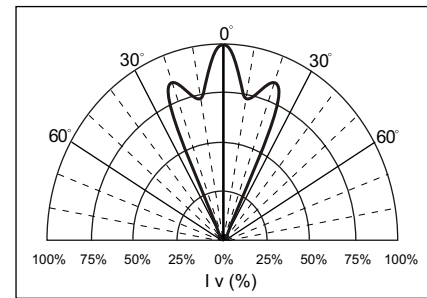
Part Number EOL-	Luminous Intensity I_v (mcd) @ $I_f = 20$ mA		Viewing Angle $2\theta_{1/2}$	Dominant Wavelength λ_D (nm) @ $I_f = 20$ mA	V_F @ $I_f = 20$ mA		I_R (μ A) @ $V_R = 5V$	Stand Off	Epoxy Color
	Min.	Typ.	Typ.	Typ.	Typ.	Max.	Max.		
55YKCC0-DG	580	1050	45°	589	2.0	2.4	10	No	Clear

BIN#	Q	R	S		
Intensity(mcd) @ $I_f = 20$ mA	580-810	810-1135	1135-1590		

Package Dimensions



Beam Pattern



Note:

- All dimensions are in millimeter (mm).
- Unspecified tolerance: ± 0.20 mm.
- Protruded resin 1.5mm max.
- Lead spacing is measured where the leads emerge from the package
- Specifications are subject to change without notice.

Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

Parameter	Symbol		<i>USER---APPROVED</i>
Peak Forward Current	I_{fm}	100mA	
Average Forward Current	I_f	30mA	
Reverse Voltage	V_r	5V	
Operating Temperature Range	T_{opr}	-40°C to + 85°C	
Storage Temperature Range	T_{sto}	-40°C to + 100°C	
Lead Soldering Temperature	T_{sol}	260°C / 5 Secondes	

Notes: a. Duty Ratio = 1/10, Pulse Width = 0.1 ms.
b. Design of heat dissipation should be considered.